

06-11-2001

IT

U.S. DEPARTMENT OF COMMERCE

Patent and Trademark Office

Docket No.: 50090-298



To the Honorable Commissioner for

101744938

Attached original documents or copy thereto:

## 1. Name of Conveying Parties:

Takashi YAMASHITA, Takeru MATSUOKA, and Shigeki  
SUNADA

05/29/01

## 2. Name and address of receiving parties:

Name: MITSUBISHI DENKI KABUSHIKI KAISHA

Address: 2-3, Marunouchi 2-Chome

Chiyoda-Ku

Tokyo 100-8310, JAPAN

Name: RYODEN SEMICONDUCTOR SYSTEM

ENGINEERING CORPORATION

Address: 1 Mizuhara 4-Chome

Itami-Shi

Hyogo 664-0005 JAPAN

JC971 U.S. PTO  
09/865501  
05/29/01Additional names of conveying parties attached? ☐ Yes

## 3. Nature of Conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other

Execution Date: May 7, 2001

Additional names & addresses attached? ☐ Yes

## 4. Application number or patent number:

If the document is being filed together with a new application, the execution date of the application is: May 7, 2001

A. Patent Application No.

69/865501

B. Patent No.

Additional numbers attached? ☐ Yes

## 5. Name and address of party to whom correspondence

Name: MCDERMOTT, WILL &amp; EMERY

Internal Address:

Street Address: 600 13<sup>th</sup> Street, N.W.

City: Washington State: DC Zip: 20005

06/08/2001 AAHMED1 00000144 500417 09865501

## 6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41)

\$40.00

☐ Enclosed☒ Authorized to be charged to deposit account

8. Deposit account number:

500417

01 FC:581

40.00 CH

DO NOT USE THIS SPACE

## 9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Stephen A. Becker, No. 26,527

May 29, 2001

Name and Registration No. of Person Signing

Signature

Date

Total number of pages comprising cover sheet: 1

CMB No. 0851-0011 (exp. 4/94)

52003201  
G 410

# ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) Takashi YAMASHITA  
(3) Shigeki SUNADA

(2) Takeru MATSUOKA

who have made a certain new and useful invention, hereby sell, assign and transfer unto

Mitsubishi Denki Kabushiki Kaisha  
2-3, Marunouchi 2-chome  
Chiyoda-ku, Tokyo 100-8310  
JAPAN

and

Ryoden Semiconductor System Engineering Corporation  
1 Mizuhara 4-chome  
Itami-shi, Hyogo 664-0005  
JAPAN

its successors and assigns ( hereinafter designated "ASSIGNEE" ) the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SEMICONDUCTOR DEVICE, AND METHOD OF MANUFACTURING THE SAME

for which an application for United States Letters Patent was executed on even date herewith,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the international Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

## INVENTORS

1) Takashi Yamashita  
Name: Takashi YAMASHITA  
2) Takeru Matsuoka  
Name: Takeru MATSUOKA  
3) Shigeki Sunada  
Name: Shigeki SUNADA

## DATE SIGNED

May 7, 2001  
May 7, 2001  
May 7, 2001